

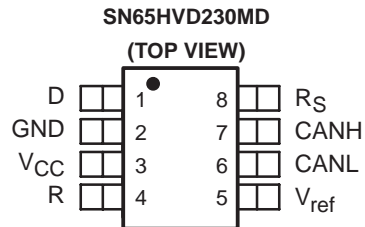
### 3.3-V CAN TRANSCEIVERS

#### FEATURES

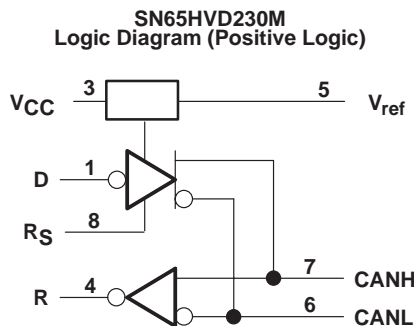
- **Controlled Baseline**
  - One Assembly/Test Site, One Fabrication Site
- **Extended Temperature Performance of –55°C to 125°C**
- **Enhanced Diminishing Manufacturing Sources (DMS) Support**
- **Enhanced Product-Change Notification**
- **Qualification Pedigree†**
- **Operates With a 3.3-V Supply**
- **Low Power Replacement for the PCA82C250 Footprint**
- **Bus/Pin ESD Protection Exceeds 15-kV HBM**
- **Controlled Driver Output Transition Times for Improved Signal Quality on the SN65HVD230M**
- **Unpowered Node Does Not Disturb the Bus**
- **Compatible With the Requirements of the ISO 11898 Standard**

- **Low-Current SN65HVD230M Standby Mode 370  $\mu$ A Typical**
- **Designed for Signaling Rates‡ Up To 1 Megabit/Second (Mbps)**
- **Thermal Shutdown Protection**
- **Open-Circuit Fail-Safe Design**

† Component qualification in accordance with JEDEC and industry standards to ensure reliable operation over an extended temperature range. This includes, but is not limited to, Highly Accelerated Stress Test (HAST) or biased 85/85, temperature cycle, autoclave or unbiased HAST, electromigration, bond intermetallic life, and mold compound life. Such qualification testing should not be viewed as justifying use of this component beyond specified performance and environmental limits.



#### logic diagram (positive logic)



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

‡ The signaling rate of a line is the number of voltage transitions that are made per second expressed in the units bps (bits per second).

**DESCRIPTION**

The SN65HVD230M controller area network (CAN) transceiver is designed for use with the Texas Instruments TMS320Lx240x 3.3-V DSPs with CAN controllers, or with equivalent devices. They are intended for use in applications employing the CAN serial communication physical layer in accordance with the ISO 11898 standard. Each CAN transceiver is designed to provide differential transmit capability to the bus and differential receive capability to a CAN controller at speeds up to 1 Mbps.

Designed for operation in especially-harsh environments, these devices feature cross-wire protection, loss-of-ground and overvoltage protection, overtemperature protection, as well as wide common-mode range.

The transceiver interfaces the single-ended CAN controller with the differential CAN bus found in industrial, building automation, and automotive applications. It operates over a  $-2\text{-V}$  to  $7\text{-V}$  common-mode range on the bus and it can withstand common-mode transients of  $\pm 25\text{ V}$ .

On the SN65HVD230M,  $R_S$  (pin 8) provides three different modes of operation: high-speed, slope control, and low-power modes. The high-speed mode of operation is selected by connecting pin 8 to ground, allowing the transmitter output transistors to switch on and off as fast as possible with no limitation on the rise and fall slopes. The rise and fall slopes can be adjusted by connecting a resistor to ground at pin 8, since the slope is proportional to the pin's output current. This slope control is implemented with external resistor values of  $10\text{ k}\Omega$ , to achieve a  $15\text{-V}/\mu\text{s}$  slew rate, to  $100\text{ k}\Omega$ , to achieve a  $2\text{-V}/\mu\text{s}$  slew rate.

The circuit of the SN65HVD230M enters a low-current standby mode during which the driver is switched off and the receiver remains active if a high logic level is applied to  $R_S$  (pin 8). The DSP controller reverses this low-current standby mode when a dominant state (bus differential voltage  $> 900\text{ mV}$  typical) occurs on the bus.

The  $V_{\text{ref}}$  (pin 5 on the SN65HVD230M) is available as a  $V_{\text{CC}}/2$  voltage reference.

**AVAILABLE OPTIONS**

<b>FUNCTION NUMBER</b>	<b>LOW POWER MODE</b>	<b>INTEGRATED SLOPE CONTROL</b>	<b>Vref PIN</b>
'230	370- $\mu\text{A}$ standby mode	Yes	Yes

<b>PART NUMBER</b>	<b>Q100</b>	<b>T<sub>A</sub></b>	<b>MARKED AS</b>
SN65HVD230MDREP	No	$-55^{\circ}\text{C}$ to $125^{\circ}\text{C}$	HV230M

**Function Tables**
**DRIVER (SN65HVD230M)**

INPUT D	RS	OUTPUTS		BUS STATE
		CANH	CANL	
L	$V_{(RS)} < 1.2\text{ V}$	H	L	Dominant
H		Z	Z	Recessive
Open	X	Z	Z	Recessive
X	$V_{(RS)} > 0.75\text{ V}_{CC}$	Z	Z	Recessive

H = high level; L = low level; X = irrelevant; ? = indeterminate

**RECEIVER (SN65HVD230M)**

DIFFERENTIAL INPUTS	RS	OUTPUT R
$V_{ID} \geq 0.9\text{ V}$	X	L
$0.5\text{ V} < V_{ID} < 0.9\text{ V}$	X	?
$V_{ID} \leq 0.5\text{ V}$	X	H
Open	X	H

H = high level; L = low level; X = irrelevant; ? = indeterminate

**TRANSCEIVER MODES (SN65HVD230M)**

$V_{(RS)}$	OPERATING MODE
$V_{(RS)} > 0.75\text{ V}_{CC}$	Standby
10 k $\Omega$ to 100 k $\Omega$ to ground	Slope control
$V_{(RS)} < 1\text{ V}$	High speed (no slope control)

**Terminal Functions**

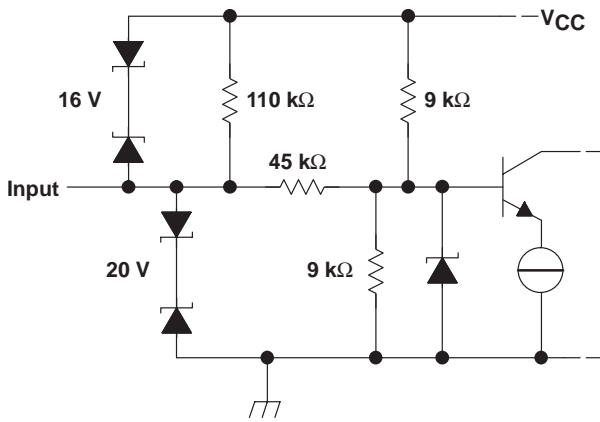
SN65HVD230M		
TERMINAL NAME	NO.	DESCRIPTION
CANL	6	Low bus output
CANH	7	High bus output
D	1	Driver input
GND	2	Ground
R	4	Receiver output
RS	8	Standby/slope control
V <sub>CC</sub>	3	Supply voltage
V <sub>ref</sub>	5	Reference output

# SN65HVD230M-EP

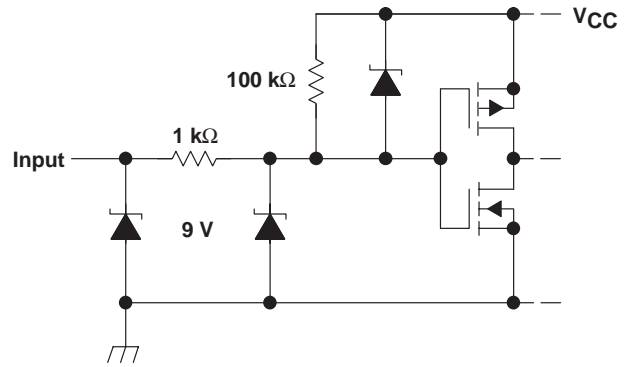
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## equivalent input and output schematic diagrams

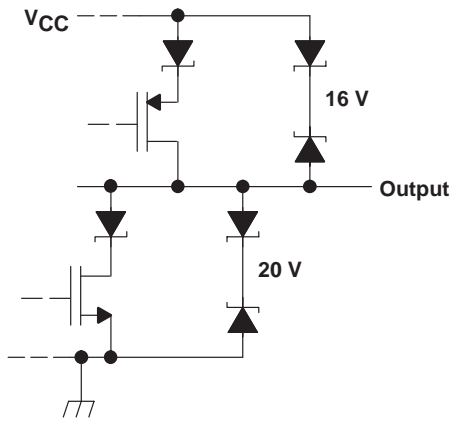
CANH and CANL Inputs



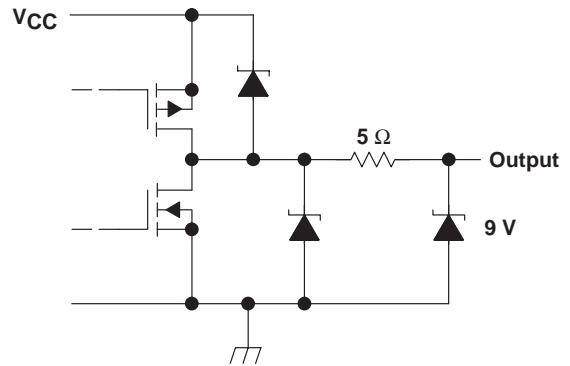
D Input



CANH and CANL Outputs



R Output



**absolute maximum ratings over operating free-air temperature (see Note 1) (unless otherwise noted)†**

Supply voltage range, $V_{CC}$	–0.3 V to 6 V
Voltage range at any bus terminal (CANH or CANL)	–7 V to 16 V
Voltage input range, transient pulse, CANH and CANL, through 100 $\Omega$ (see Figure 7)	–25 V to 25 V
Input voltage range, $V_I$ (D or R)	–0.5 V to $V_{CC} + 0.5$ V
Electrostatic discharge: Human body model (see Note 2)	CANH, CANL and GND 15 kV
	All pins 2.5 kV
Charged-device model (see Note 3)	All pins 4 kV
Continuous total power dissipation	See Dissipation Rating table
Storage temperature range, $T_{stg}$	–65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES:
1. All voltage values, except differential I/O bus voltages, are with respect to network ground terminal.
  2. Tested in accordance with JEDEC Standard 22, Test Method A114-A.
  3. Tested in accordance with JEDEC Standard 22, Test Method C101.
  4. Long-term high-temperature storage and/or extended use at maximum recommended operating conditions may result in a reduction of overall device life. See [http://www.ti.com/ep\\_quality](http://www.ti.com/ep_quality) for additional information on enhanced plastic packaging.

**DISSIPATION RATING TABLE**

PACKAGE	$T_A \leq 25^\circ\text{C}$ POWER RATING	DERATING FACTOR‡ ABOVE $T_A = 25^\circ\text{C}$	$T_A = 70^\circ\text{C}$ POWER RATING	$T_A = 85^\circ\text{C}$ POWER RATING	$T_A = 125^\circ\text{C}$ POWER RATING
D	725 mW	5.8 mW/°C	464 mW	377 mW	145 mW

‡ This is the inverse of the junction-to-ambient thermal resistance when board-mounted and with no air flow.

**recommended operating conditions**

PARAMETER		MIN	NOM	MAX	UNIT
Supply voltage, $V_{CC}$		3		3.6	V
Voltage at any bus terminal (common mode) $V_{IC}$		–2§		7	V
Voltage at any bus terminal (separately) $V_I$		–2.5		7.5	V
High-level input voltage, $V_{IH}$	D, R	2			V
Low-level input voltage, $V_{IL}$	D, R			0.8	V
Differential input voltage, $V_{ID}$ (see Figure 5)		–6		6	V
$V_{(RS)}$		0		$V_{CC}$	V
$V_{(RS)}$ for standby or sleep		0.75 $V_{CC}$		$V_{CC}$	V
Rs wave-shaping resistance		0		100	k $\Omega$
High-level output current, $I_{OH}$	Driver	–40			mA
	Receiver	–8			
Low-level output current, $I_{OL}$	Driver			48	mA
	Receiver			8	
Operating free-air temperature, $T_A$		–55		125	°C

§ The algebraic convention, in which the least positive (most negative) limit is designated as minimum is used in this data sheet.

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## driver electrical characteristics over recommended operating conditions (unless otherwise noted)

PARAMETER			TEST CONDITIONS			MIN	TYP†	MAX	UNIT
V <sub>OH</sub>	Bus output voltage	Dominant	V <sub>I</sub> = 0 V, See Figure 1 and Figure 3	CANH	2.45		V <sub>CC</sub>	V	
				CANL	0.5		1.25		
V <sub>OL</sub>		Recessive	V <sub>I</sub> = 3 V, See Figure 1 and Figure 3	CANH		2.3			
				CANL		2.3			
V <sub>OD(D)</sub>	Differential output voltage	Dominant	V <sub>I</sub> = 0 V, See Figure 1		1.5	2	3	V	
			V <sub>I</sub> = 0 V, See Figure 2		1.2	2	3		
V <sub>OD(R)</sub>		Recessive	V <sub>I</sub> = 3 V, See Figure 1		-120	0	12	mV	
			V <sub>I</sub> = 3 V, No load		-0.5	-0.2	0.05	V	
I <sub>IH</sub>	High-level input current	V <sub>I</sub> = 2 V			-30			μA	
I <sub>IL</sub>	Low-level input current	V <sub>I</sub> = 0.8 V			-30			μA	
I <sub>OS</sub>	Short-circuit output current	V <sub>CANH</sub> = -2 V			-250		250	mA	
		V <sub>CANL</sub> = 7 V			-250		250		
C <sub>O</sub>	Output capacitance	See receiver							
I <sub>CC</sub>	Supply current	Standby	SN65HVD230M	V <sub>(RS)</sub> = V <sub>CC</sub>			370	600	μA
		All devices	Dominant	V <sub>I</sub> = 0 V, No load	Dominant		10	17	mA
			Recessive	V <sub>I</sub> = V <sub>CC</sub> , No load	Recessive		10	17	

† All typical values are at 25°C and with a 3.3-V supply.

## driver switching characteristics at T<sub>A</sub> = 25°C (unless otherwise noted)

PARAMETER		TEST CONDITIONS			MIN	TYP	MAX	UNIT
t <sub>PLH</sub>	Propagation delay time, low-to-high-level output	V <sub>(RS)</sub> = 0 V				35	85	ns
		R <sub>S</sub> with 10 kΩ to ground				70	190	
		R <sub>S</sub> with 100 kΩ to ground				500	870	
t <sub>PHL</sub>	Propagation delay time, high-to-low-level output	V <sub>(RS)</sub> = 0 V				70	130	ns
		R <sub>S</sub> with 10 kΩ to ground				130	205	
		R <sub>S</sub> with 100 kΩ to ground				870	1200	
t <sub>sk(p)</sub>	Pulse skew ( t <sub>P(HL)</sub> - t <sub>P(LH)</sub>  )	V <sub>(RS)</sub> = 0 V				35		ns
		R <sub>S</sub> with 10 kΩ to ground			C <sub>L</sub> = 50 pF, See Figure 4	60		
		R <sub>S</sub> with 100 kΩ to ground				370		
t <sub>r</sub>	Differential output signal rise time	V <sub>(RS)</sub> = 0 V			25	50	100	ns
t <sub>f</sub>	Differential output signal fall time	V <sub>(RS)</sub> = 0 V			40	55	80	ns
t <sub>r</sub>	Differential output signal rise time	R <sub>S</sub> with 10 kΩ to ground			75	120	160	ns
t <sub>f</sub>	Differential output signal fall time				80	125	150	ns
t <sub>r</sub>	Differential output signal rise time	R <sub>S</sub> with 100 kΩ to ground			350	800	1200	ns
t <sub>f</sub>	Differential output signal fall time				600	825	1200	ns

receiver electrical characteristics over recommended operating conditions (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP†	MAX	UNIT
V <sub>IT+</sub>	Positive-going input threshold voltage	See Table 1		750	900	mV
V <sub>IT-</sub>	Negative-going input threshold voltage			500	650	mV
V <sub>hys</sub>	Hysteresis voltage (V <sub>IT+</sub> – V <sub>IT-</sub> )			100		
V <sub>OH</sub>	High-level output voltage	-6 V ≤ V <sub>ID</sub> ≤ 500 mV, I <sub>O</sub> = -8 mA, See Figure 5	2.4			V
V <sub>OL</sub>	Low-level output voltage	900 mV ≤ V <sub>ID</sub> ≤ 6 V, I <sub>O</sub> = 8 mA, See Figure 5			0.4	
I <sub>I</sub>	Bus input current	V <sub>IH</sub> = 7 V	Other input at 0 V, D = 3 V	100	250	μA
		V <sub>IH</sub> = 7 V, V <sub>CC</sub> = 0 V		100	350	
		V <sub>IH</sub> = -2 V		-200	-30	μA
		V <sub>IH</sub> = -2 V, V <sub>CC</sub> = 0 V		-100	-20	
C <sub>i</sub>	CANH, CANL input capacitance	Pin-to-ground, V <sub>I</sub> = 0.4 sin(4E6πt) + 0.5 V	V <sub>(D)</sub> = 3 V,		32	pF
C <sub>diff</sub>	Differential input capacitance	Pin-to-pin, V <sub>I</sub> = 0.4 sin(4E6πt) + 0.5 V	V <sub>(D)</sub> = 3 V,		16	pF
R <sub>diff</sub>	Differential input resistance	Pin-to-pin, V <sub>(D)</sub> = 3 V	40	70	100	kΩ
R <sub>T</sub>	CANH, CANL input resistance		20	35	50	kΩ
I <sub>CC</sub>	Supply current	See driver				

† All typical values are at 25°C and with a 3.3-V supply.

receiver switching characteristics at T<sub>A</sub> = 25°C (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
t <sub>PLH</sub>	Propagation delay time, low-to-high-level output	See Figure 6		35	55	ns
t <sub>PHL</sub>	Propagation delay time, high-to-low-level output			35	55	
t <sub>sk(p)</sub>	Pulse skew ( t <sub>P(HL)</sub> – t <sub>P(LH)</sub>  )				10	
t <sub>r</sub>	Output signal rise time	See Figure 6		1.5		ns
t <sub>f</sub>	Output signal fall time			1.5		
t <sub>(loop)</sub>	Total loop delay, driver input to receiver output	V <sub>(RS)</sub> = 0 V		70	135	ns
t <sub>(loop)</sub>	Total loop delay, driver input to receiver output	R <sub>S</sub> with 10 kΩ to ground		105	175	
t <sub>(loop)</sub>	Total loop delay, driver input to receiver output	R <sub>S</sub> with 100 kΩ to ground		535	920	

device control-pin characteristics over recommended operating conditions (unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP†	MAX	UNIT
$t_{(WAKE)}$	SN65HVD230M wake-up time from standby mode with $R_S$		0.55	1.5	$\mu S$
$V_{ref}$	Reference output voltage	$-5 \mu A < I(V_{ref}) < 5 \mu A$		$0.45 V_{CC}$	$0.55 V_{CC}$
		$-50 \mu A < I(V_{ref}) < 50 \mu A$		$0.4 V_{CC}$	$0.6 V_{CC}$
$I_{(RS)}$	Input current for high-speed	$V_{(RS)} < 1 V$		-450	0

† All typical values are at 25°C and with a 3.3 V supply.

PARAMETER MEASUREMENT INFORMATION

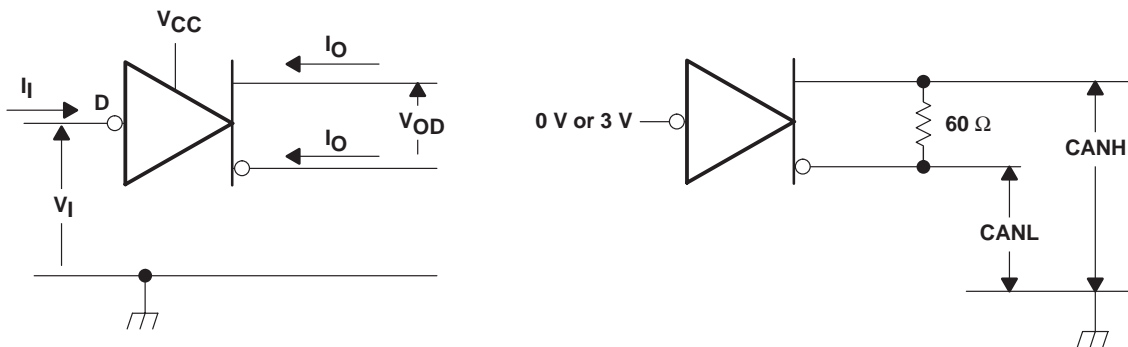


Figure 1. Driver Voltage and Current Definitions

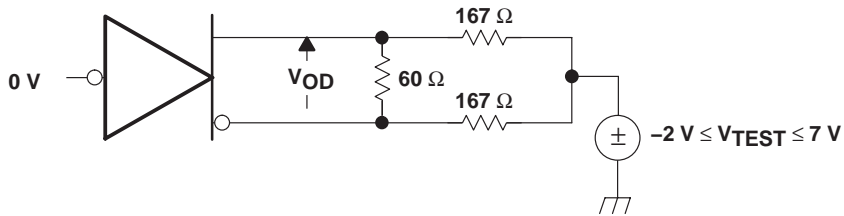


Figure 2. Driver  $V_{OD}$

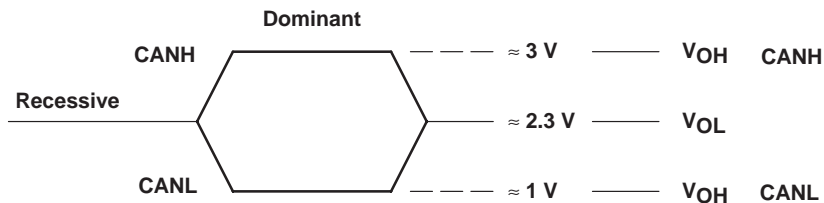
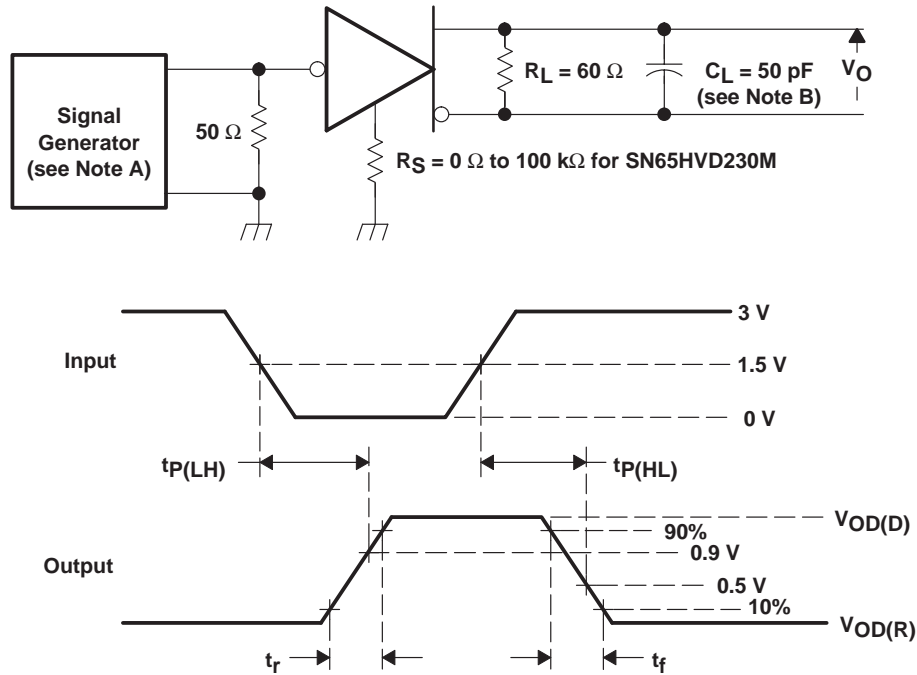


Figure 3. Driver Output Voltage Definitions



PARAMETER MEASUREMENT INFORMATION



- NOTES: A. The input pulse is supplied by a generator having the following characteristics: PRR ≤ 500 kHz, 50% duty cycle,  $t_r \leq 6$  ns,  $t_f \leq 6$  ns,  $Z_0 = 50 \Omega$ .  
 B.  $C_L$  includes probe and jig capacitance.

Figure 4. Driver Test Circuit and Voltage Waveforms

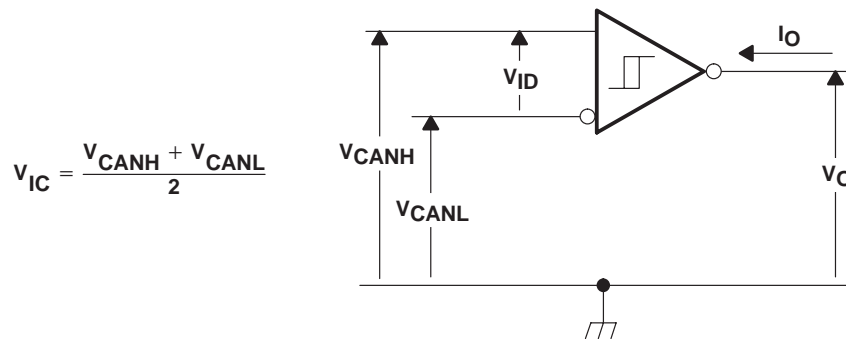
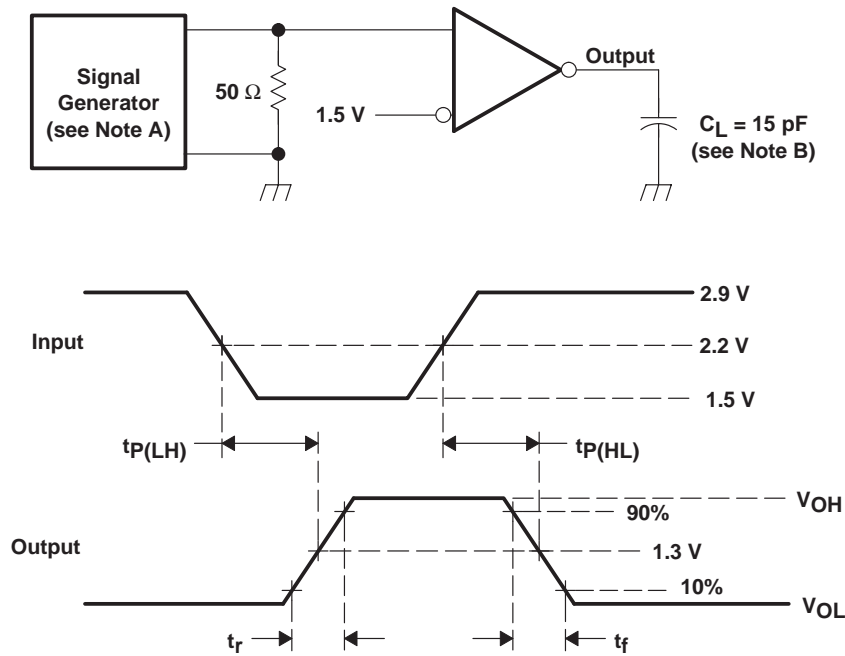


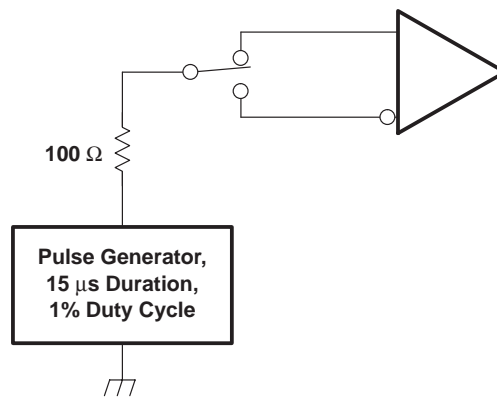
Figure 5. Receiver Voltage and Current Definitions

**PARAMETER MEASUREMENT INFORMATION**



- NOTES: A. The input pulse is supplied by a generator having the following characteristics:  $PRR \leq 500 \text{ kHz}$ , 50% duty cycle,  $t_r \leq 6 \text{ ns}$ ,  $t_f \leq 6 \text{ ns}$ ,  $Z_o = 50 \Omega$ .  
 B.  $C_L$  includes probe and jig capacitance.

**Figure 6. Receiver Test Circuit and Voltage Waveforms**

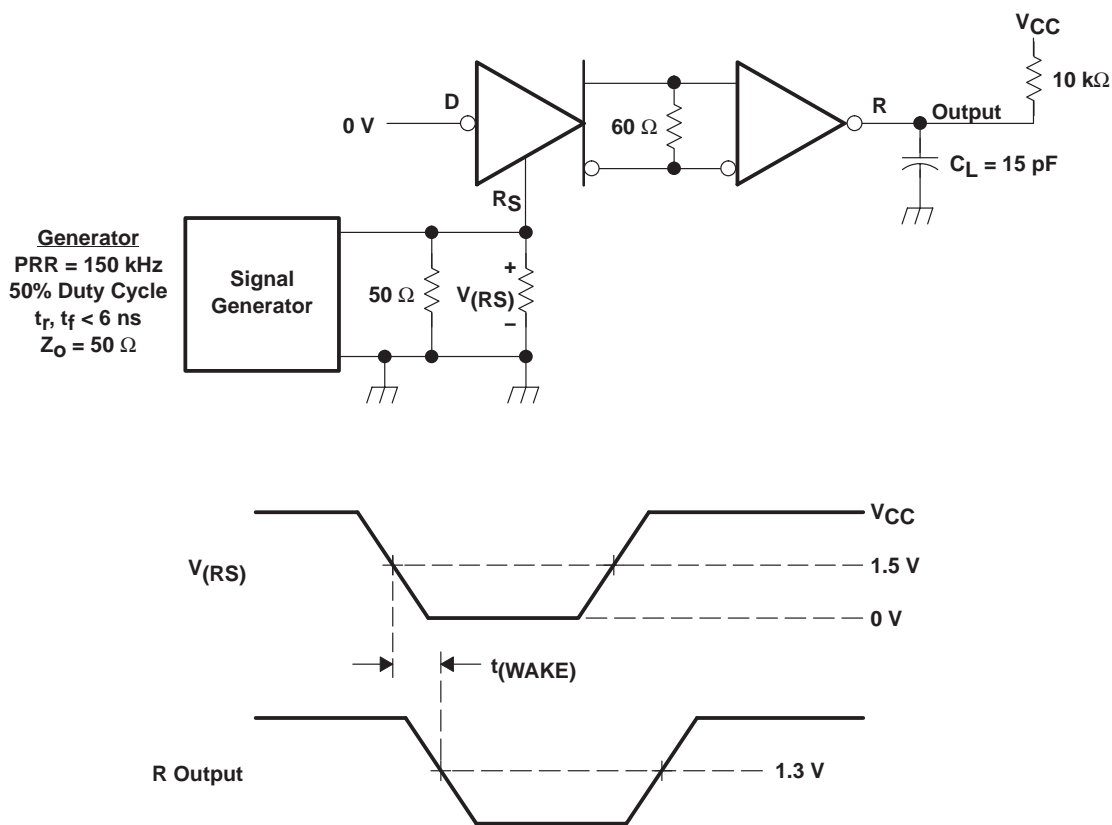


**Figure 7. Overvoltage Protection**

PARAMETER MEASUREMENT INFORMATION

Table 1. Receiver Characteristics Over Common Mode With V(RS) at 1.2 V

V <sub>IC</sub>	V <sub>ID</sub>	V <sub>CANH</sub>	V <sub>CANL</sub>	R OUTPUT	
-2 V	900 mV	-1.55 V	-2.45 V	L	V <sub>OL</sub>
7 V	900 mV	8.45 V	6.55 V	L	
1 V	6 V	4 V	-2 V	L	
4 V	6 V	7 V	1 V	L	
-2 V	500 mV	-1.75 V	-2.25 V	H	V <sub>OH</sub>
7 V	500 mV	7.25 V	6.75 V	H	
1 V	-6 V	-2 V	4 V	H	
4 V	-6 V	1 V	7 V	H	
X	X	Open	Open	H	



TYPICAL CHARACTERISTICS

SUPPLY CURRENT (RMS)  
vs  
FREQUENCY

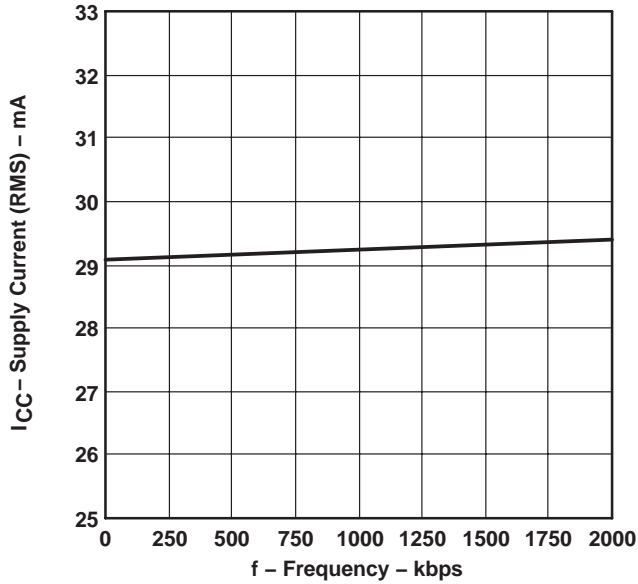


Figure 9

LOGIC INPUT CURRENT (D PIN)  
vs  
INPUT VOLTAGE

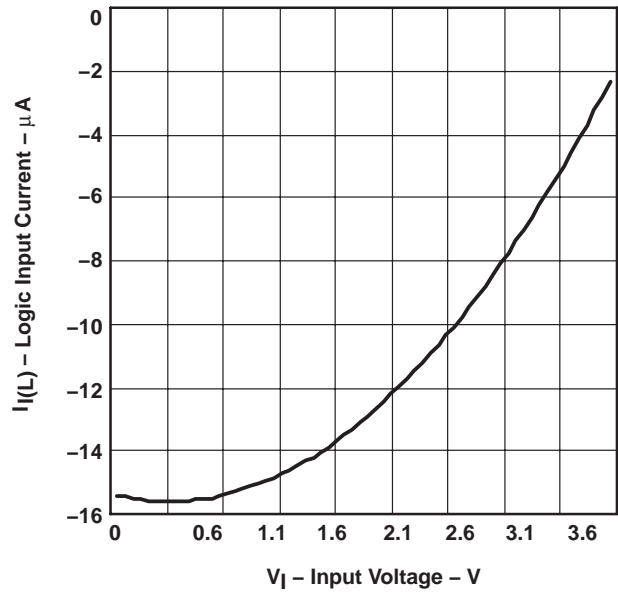


Figure 10

BUS INPUT CURRENT  
vs  
BUS INPUT VOLTAGE

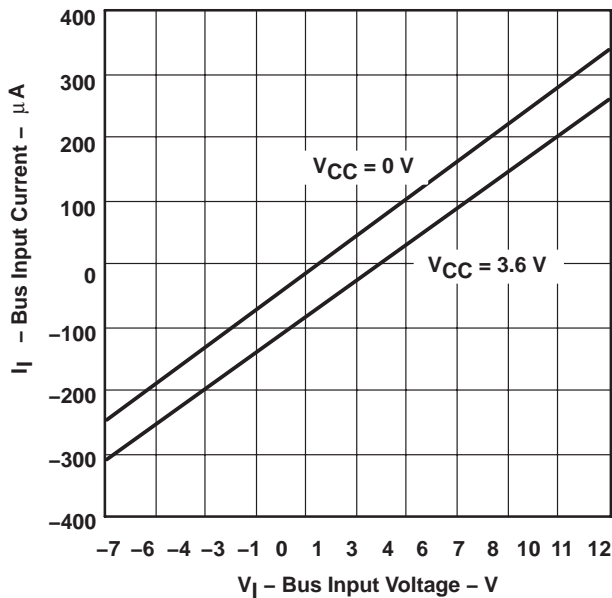


Figure 11

DRIVER LOW-LEVEL OUTPUT CURRENT  
vs  
LOW-LEVEL OUTPUT VOLTAGE

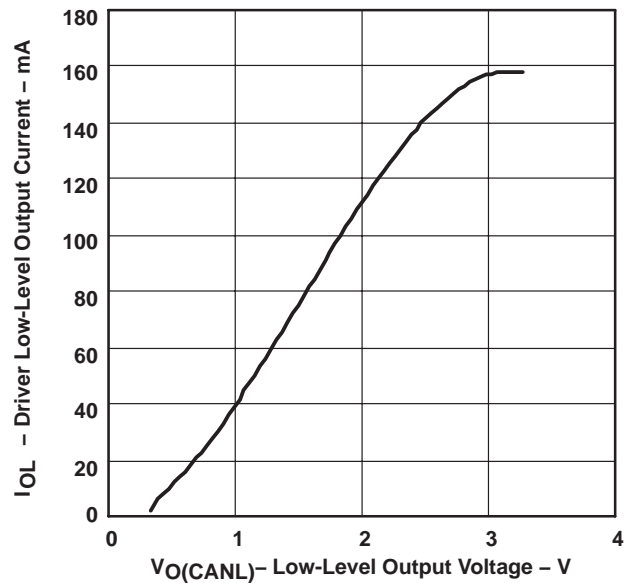


Figure 12

TYPICAL CHARACTERISTICS

DRIVER HIGH-LEVEL OUTPUT CURRENT  
vs  
HIGH-LEVEL OUTPUT VOLTAGE

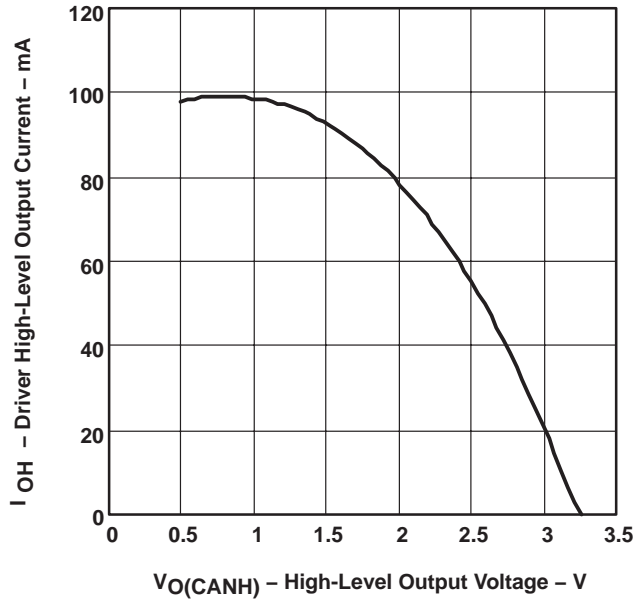


Figure 13

DOMINANT VOLTAGE (VOD)  
vs  
FREE-AIR TEMPERATURE

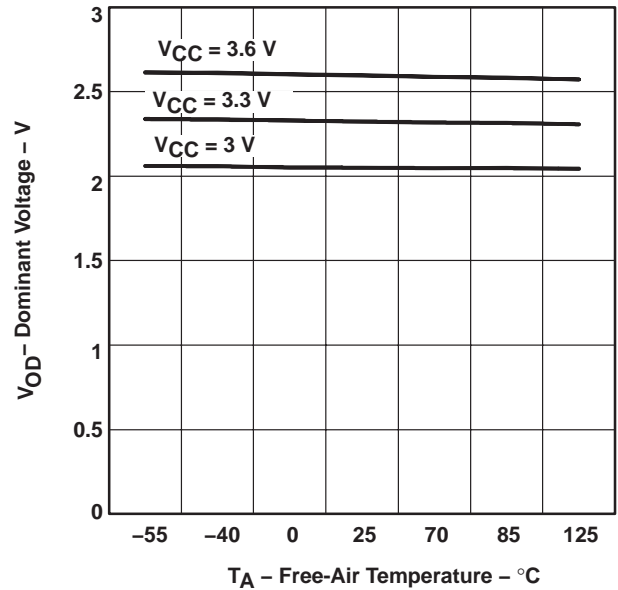


Figure 14

RECEIVER LOW-TO-HIGH PROPAGATION DELAY TIME  
vs  
FREE-AIR TEMPERATURE

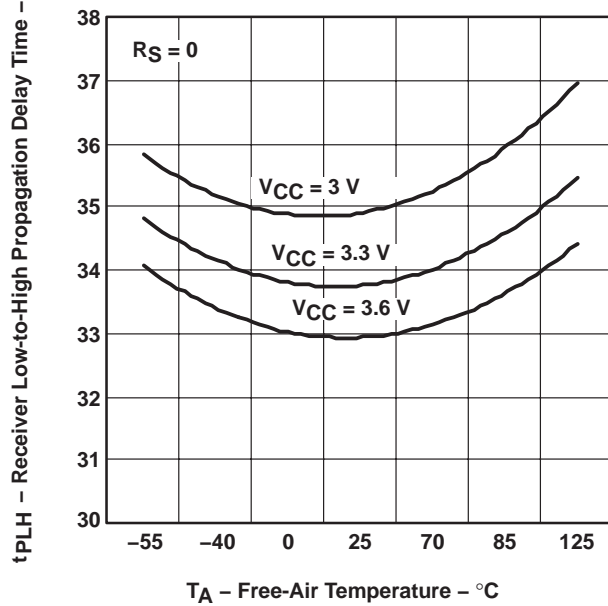


Figure 15

RECEIVER HIGH-TO-LOW PROPAGATION DELAY TIME  
vs  
FREE-AIR TEMPERATURE

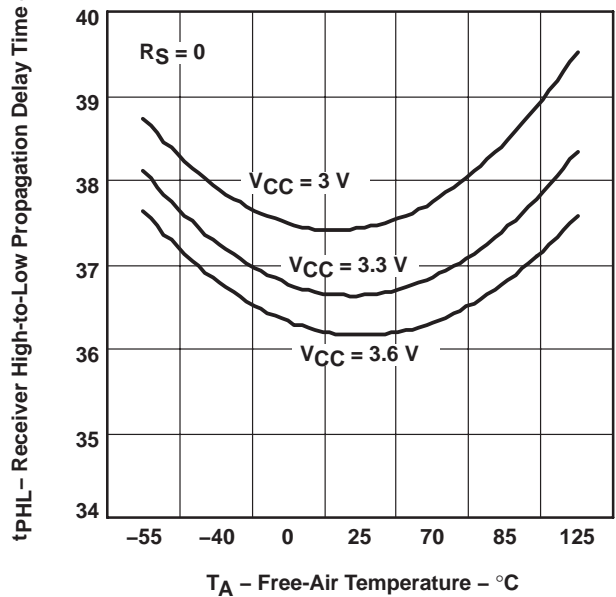


Figure 16

TYPICAL CHARACTERISTICS

DRIVER LOW-TO-HIGH PROPAGATION DELAY TIME  
vs  
FREE-AIR TEMPERATURE

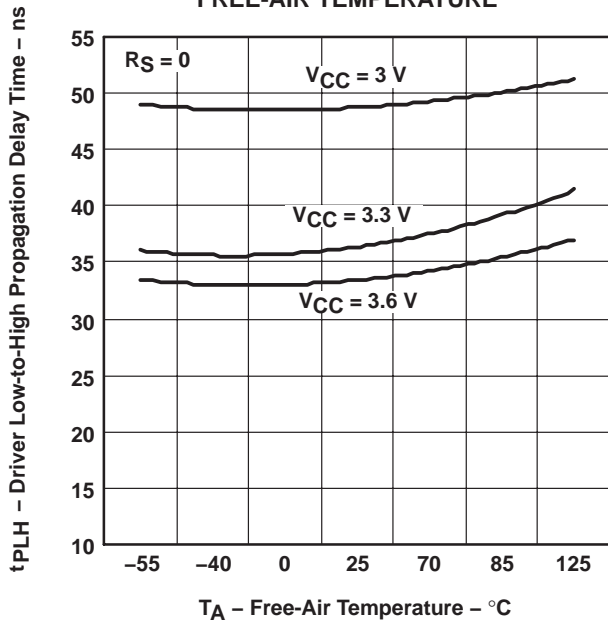


Figure 17

DRIVER HIGH-TO-LOW PROPAGATION DELAY TIME  
vs  
FREE-AIR TEMPERATURE

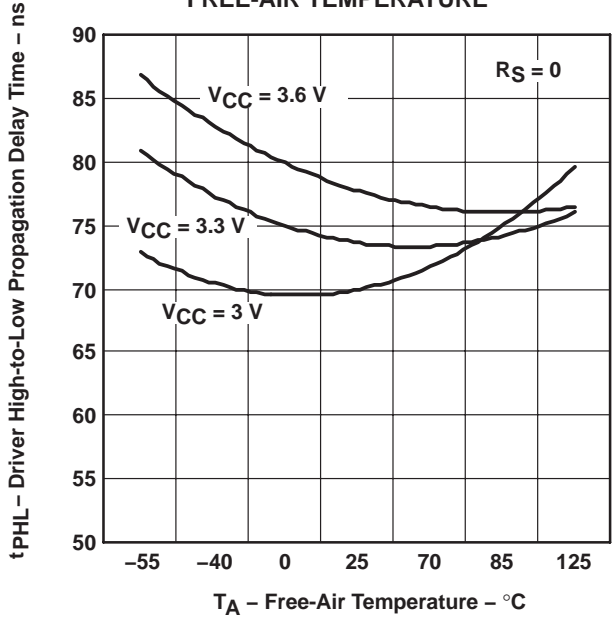


Figure 18

DRIVER LOW-TO-HIGH PROPAGATION DELAY TIME  
vs  
FREE-AIR TEMPERATURE

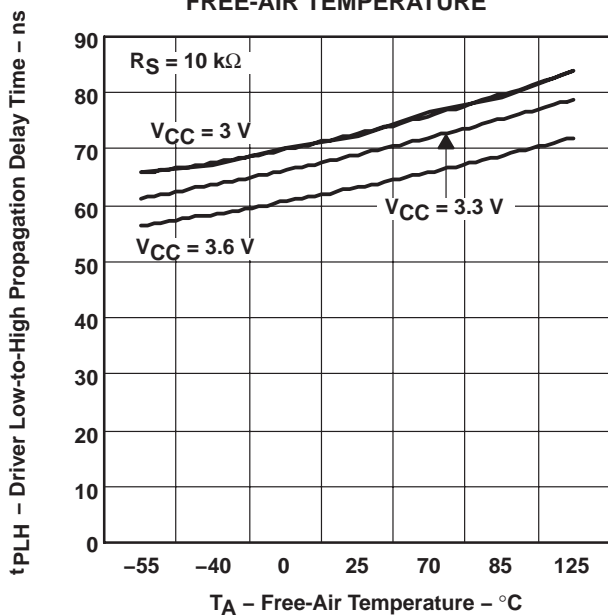


Figure 19

DRIVER HIGH-TO-LOW PROPAGATION DELAY TIME  
vs  
FREE-AIR TEMPERATURE

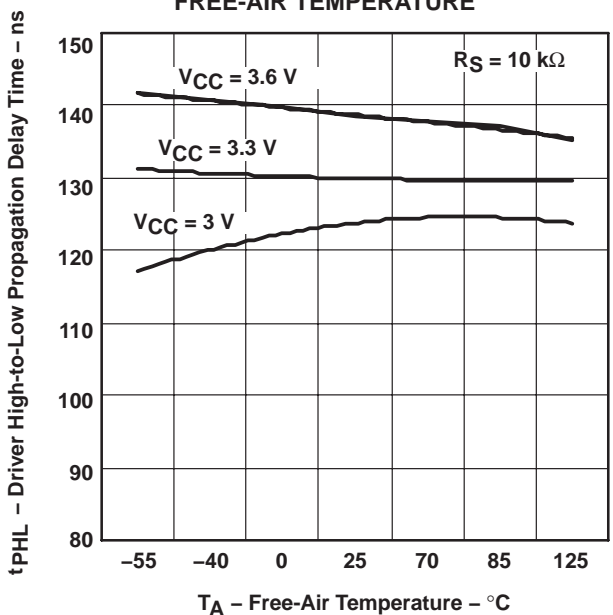


Figure 20

TYPICAL CHARACTERISTICS

DRIVER LOW-TO-HIGH PROPAGATION DELAY TIME  
vs  
FREE-AIR TEMPERATURE

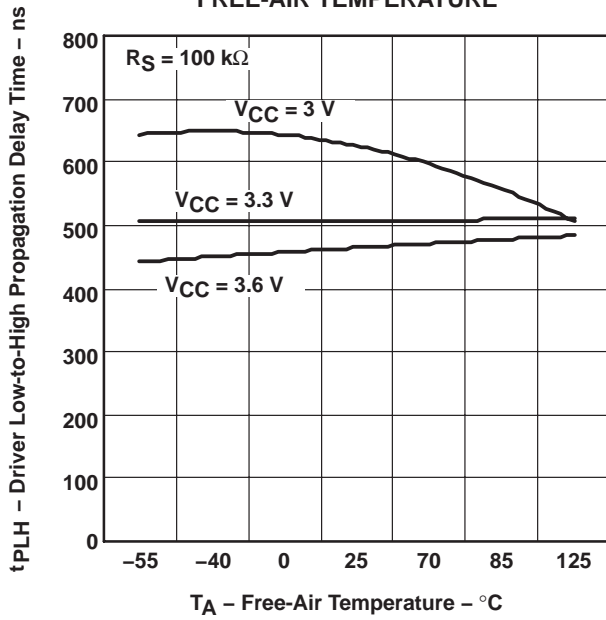


Figure 21

DRIVER HIGH-TO-LOW PROPAGATION DELAY TIME  
vs  
FREE-AIR TEMPERATURE

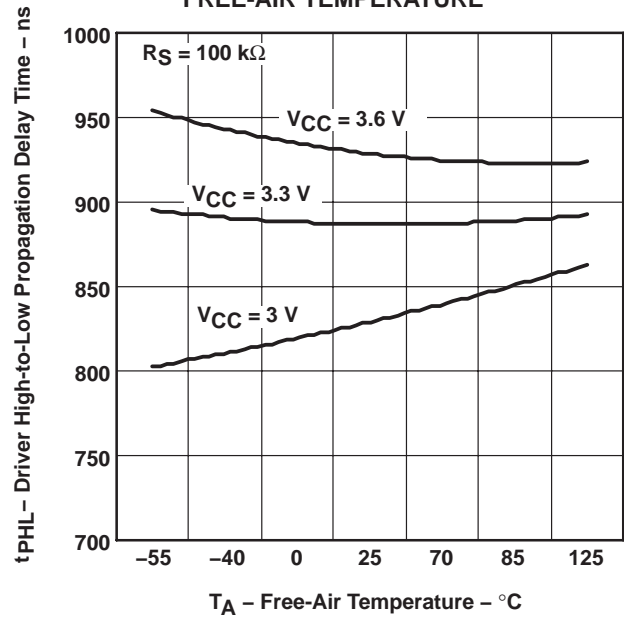


Figure 22

DRIVER OUTPUT CURRENT  
vs  
SUPPLY VOLTAGE

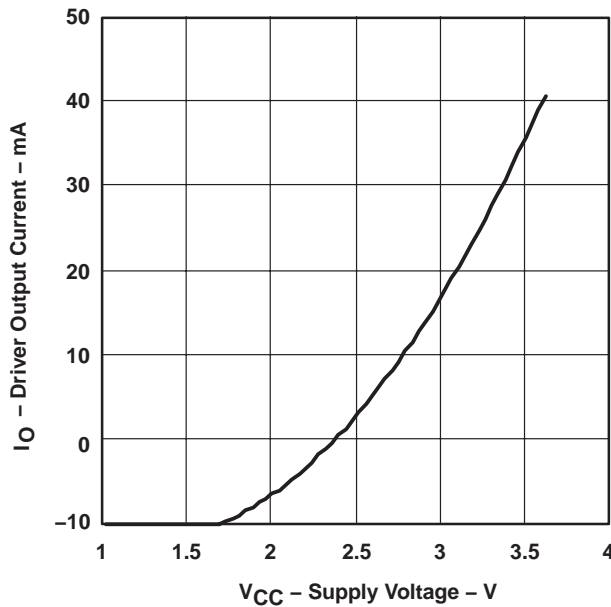


Figure 23

DIFFERENTIAL DRIVER OUTPUT FALL TIME  
vs Source Resistance ( $R_S$ )

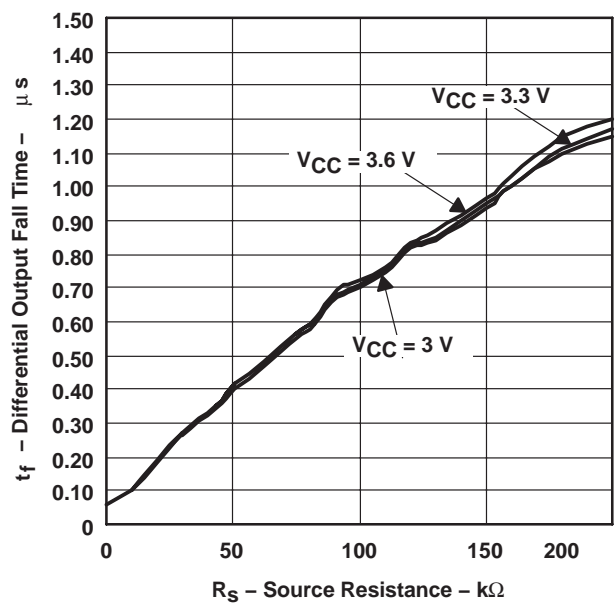


Figure 24

TYPICAL CHARACTERISTICS

REFERENCE VOLTAGE  
vs  
REFERENCE CURRENT

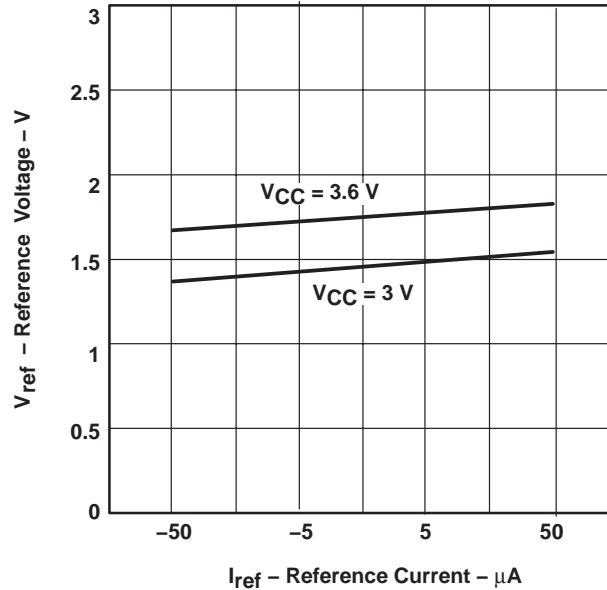


Figure 25

APPLICATION INFORMATION

This application provides information concerning the implementation of the physical medium attachment layer in a CAN network according to the ISO 11898 standard. It presents a typical application circuit and test results, as well as discussions on slope control, total loop delay, and interoperability in 5-V systems.

introduction

ISO 11898 is the international standard for high-speed serial communication using the controller area network (CAN) bus protocol. It supports multimaster operation, real-time control, programmable data rates up to 1 Mbps, and powerful redundant error checking procedures that provide reliable data transmission. It is suited for networking *intelligent* devices as well as sensors and actuators within the rugged electrical environment of a machine chassis or factory floor. The SN65HVD230M family of 3.3-V CAN transceivers implement the lowest layers of the ISO/OSI reference model. This is the interface with the physical signaling output of the CAN controller of the Texas Instruments TMS320Lx240x 3.3-V DSPs, as illustrated in Figure 26.



APPLICATION INFORMATION

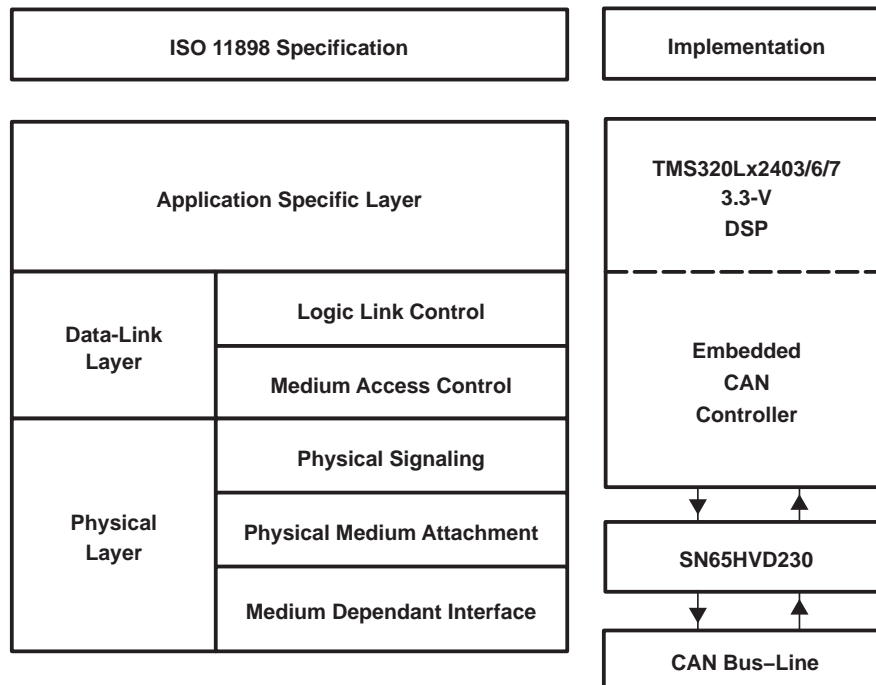


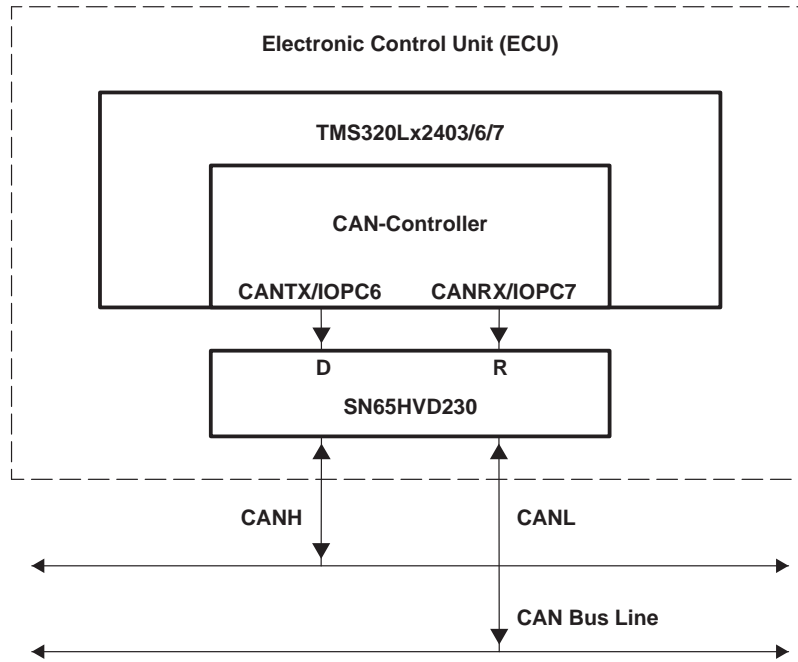
Figure 26. The Layered ISO 11898 Standard Architecture

The SN65HVD230M family of CAN transceivers are compatible with the ISO 11898 standard; this ensures interoperability with other standard-compliant products.

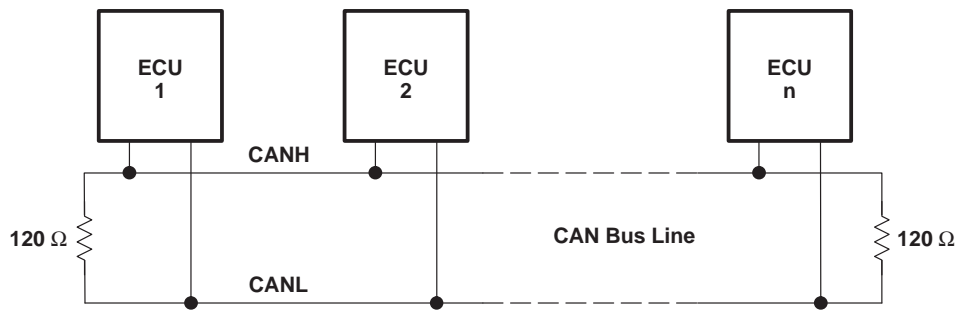
application of the SN65HVD230M

Figure 27 illustrates a typical application of the SN65HVD230M family. The output of a DSP's CAN controller is connected to the serial driver input, pin D, and receiver serial output, pin R, of the transceiver. The transceiver is then attached to the differential bus lines at pins CANH and CANL. Typically, the bus is a twisted pair of wires with a characteristic impedance of 120 Ω, in the standard half-duplex multipoint topology of Figure 28. Each end of the bus is terminated with 120-Ω resistors in compliance with the standard to minimize signal reflections on the bus.

**APPLICATION INFORMATION**



**Figure 27. Details of a Typical CAN Node**



**Figure 28. Typical CAN Network**

The SN65HVD230M 3.3-V CAN transceivers provide the interface between the 3.3-V TMS320Lx2403/6/7 CAN DSPs and the differential bus line, and are designed to transmit data at signaling rates up to 1 Mbps as defined by the ISO 11898 standard.

**features of the SN65HVD230M**

These transceivers feature 3.3-V operation and standard compatibility with signaling rates up to 1 Mbps, and also offer 16-kV HBM ESD protection on the bus pins, thermal shutdown protection, bus fault protection, and open-circuit receiver failsafe. The failsafe design of the receiver assures a logic high at the receiver output if the bus wires become open circuited. If a high ambient operating environment temperature or excessive output current result in thermal shutdown, the bus pins become high impedance, while the D and R pins default to a logic high.

## APPLICATION INFORMATION

## features of the SN65HVD230M (continued)

The bus pins are also maintained in a high-impedance state during low  $V_{CC}$  conditions to ensure glitch-free power-up and power-down bus protection for hot-plugging applications. This high-impedance condition also means that an unpowered node will not disturb the bus. Transceivers without this feature usually have a low output impedance. This results in a high current demand when the transceiver is unpowered, a condition that could affect the entire bus.

## operating modes

$R_S$  (pin 8) of the SN65HVD230M provides for three different modes of operation: high-speed mode, slope-control mode, and low-power standby mode.

## high-speed mode

The high-speed mode can be selected by applying a logic low to  $R_S$  (pin 8). The high-speed mode of operation is commonly employed in industrial applications. High-speed allows the output to switch as fast as possible with no internal limitation on the output rise and fall slopes. The only limitations of the high-speed operation are cable length and radiated emission concerns, each of which is addressed by the slope control mode of operation.

If the low-power standby mode is to be employed in the circuit, direct connection to a DSP output pin can be used to switch between a logic-low level ( $< 1\text{ V}$ ) for high speed mode operation, and the logic-high level ( $> 0.75\text{ V}_{CC}$ ) for standby mode operation. Figure 29 shows a typical DSP connection and Figure 30 shows the SN65HVD230M driver output signal in high-speed mode on the CAN bus.

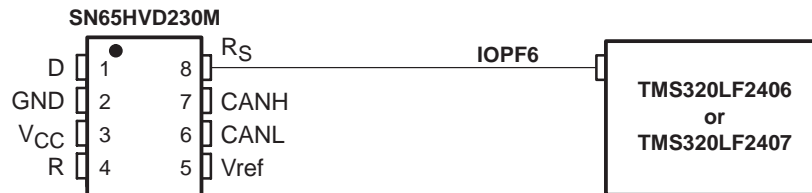


Figure 29.  $R_S$  (Pin 8) Connection to a TMS320LF2406/07 for High-Speed or Standby Mode Operation

APPLICATION INFORMATION

high-speed mode (continued)

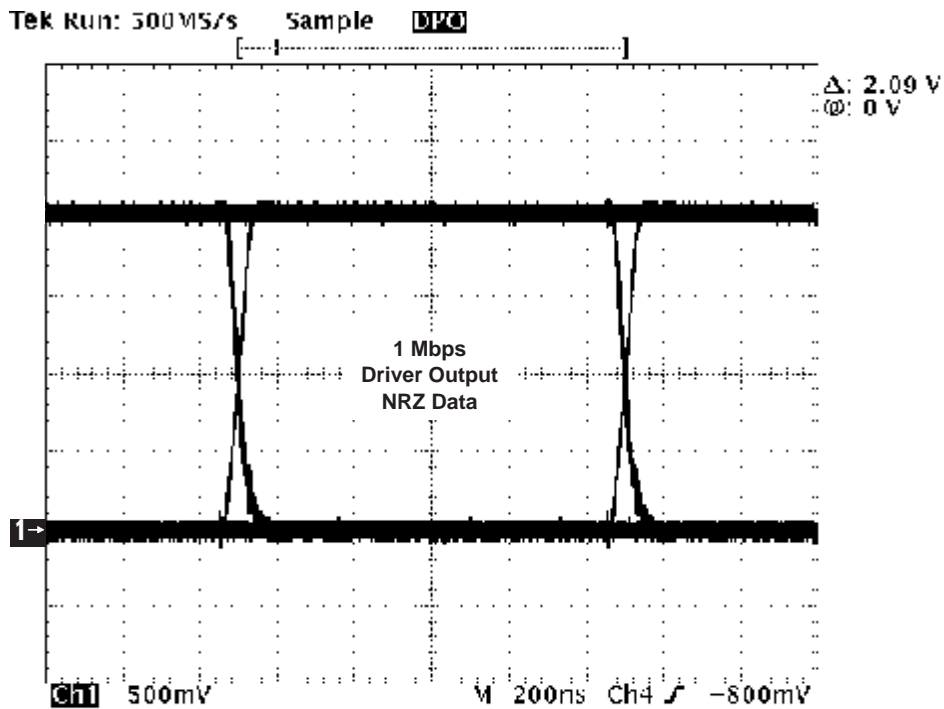


Figure 30. Typical SN65HVD230M High-Speed Mode Output Waveform Into a 60-Ω Load

slope-control mode

Electromagnetic compatibility is essential in many applications using unshielded bus cable to reduce system cost. To reduce the electromagnetic interference generated by fast rise times and resulting harmonics, the rise and fall slopes of the SN65HVD230M driver outputs can be adjusted by connecting a resistor from  $R_S$  (pin 8) to ground or to a logic low voltage, as shown in Figure 31. The slope of the driver output signal is proportional to the pin's output current. This slope control is implemented with an external resistor value of 10 kΩ to achieve a  $\approx 15$  V/μs slew rate, and up to 100 kΩ to achieve a  $\approx 2$  V/μs slew rate as displayed in Figure 32. Typical driver output waveforms from a pulse input signal with and without slope control are displayed in Figure 33. A pulse input is used rather than NRZ data to clearly display the actual slew rate.

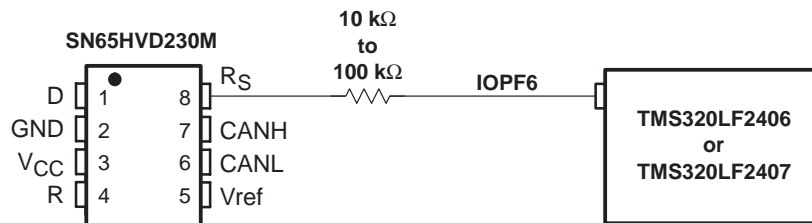


Figure 31. Slope-Control or Standby Mode Connection to a DSP

APPLICATION INFORMATION

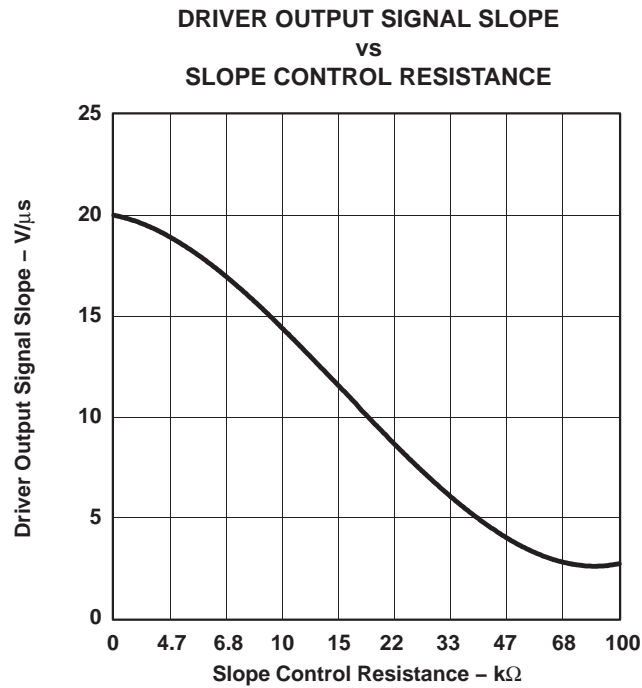


Figure 32. SN65HVD230M Driver Output Signal Slope vs Slope Control Resistance Value

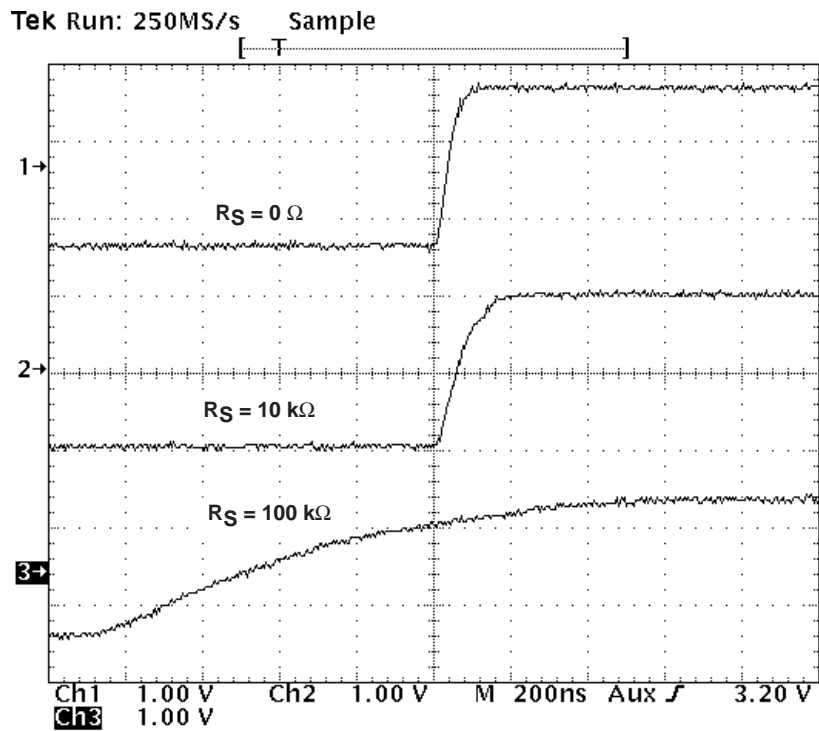


Figure 33. Typical SN65HVD230M 250-kbps Output Pulse Waveforms With Slope Control

## APPLICATION INFORMATION

### standby mode (listen only mode) of the SN65HVD230M

If a logic high ( $> 0.75 V_{CC}$ ) is applied to  $R_S$  (pin 8) in Figure 29 and Figure 31, the circuit of the SN65HVD230M enters a low-current, *listen only* standby mode during which the driver is switched off and the receiver remains active. In this *listen only* state, the transceiver is completely passive to the bus. It makes no difference if a slope control resistor is in place as shown in Figure 31. The DSP can reverse this low-power standby mode when the rising edge of a dominant state (bus differential voltage  $> 900$  mV typical) occurs on the bus. The DSP, sensing bus activity, reactivates the driver circuit by placing a logic low ( $< 1.2$  V) on  $R_S$  (pin 8).

### loop propagation delay

Transceiver loop delay is a measure of the overall device propagation delay, consisting of the delay from the driver input to the differential outputs, plus the delay from the receiver inputs to its output.

The loop delay of the transceiver displayed in Figure 34 increases accordingly when slope control is being used. This increased loop delay means that the total bus length must be reduced to meet the CAN bit-timing requirements of the overall system. The loop delay becomes  $\approx 100$  ns when employing slope control with a 10-k $\Omega$  resistor, and  $\approx 500$  ns with a 100-k $\Omega$  resistor. Therefore, considering that the rule-of-thumb propagation delay of typical bus cable is 5 ns/m, slope control with the 100-k $\Omega$  resistor decreases the allowable bus length by the difference between the 500-ns max loop delay and the loop delay with no slope control, 70.7 ns. This equates to  $(500 - 70.7 \text{ ns}) / 5 \text{ ns}$ , or approximately 86 m less bus length. This slew-rate/bus length trade-off to reduce electromagnetic interference to adjoining circuits from the bus can also be solved with a high-quality shielded bus cable.

APPLICATION INFORMATION

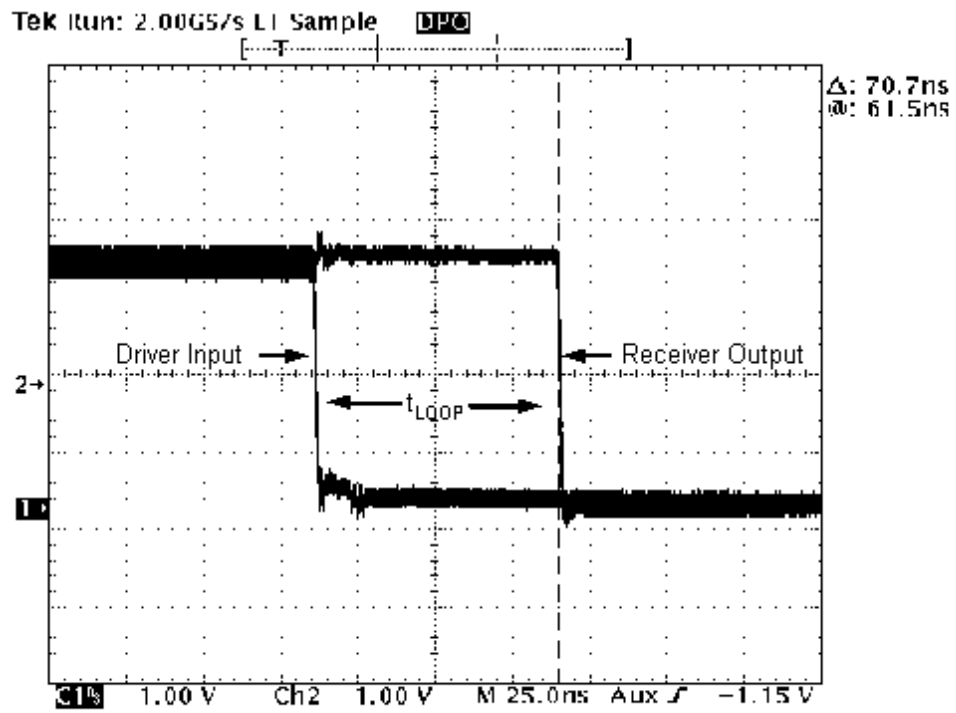
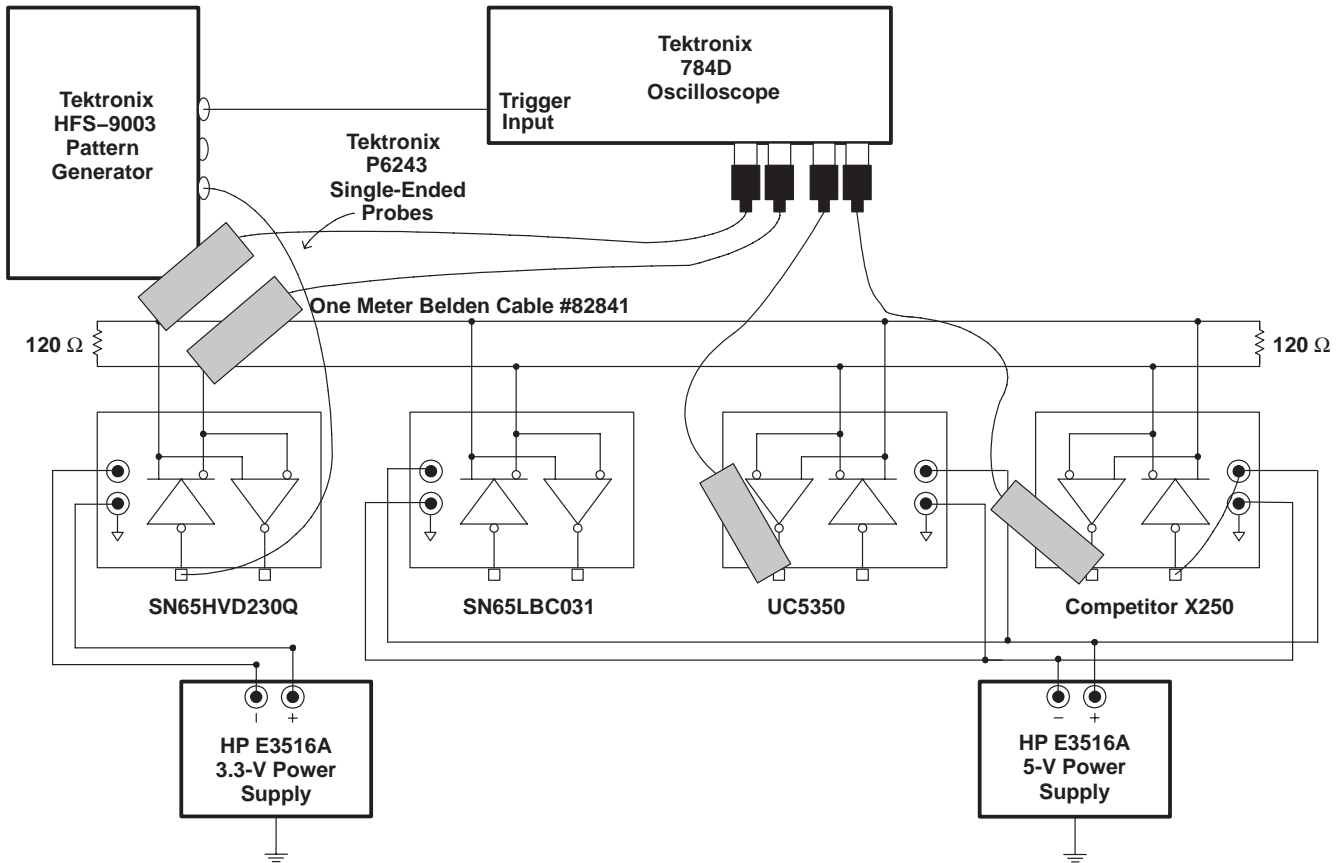


Figure 34. 70.7-ns Loop Delay Through the SN65HVD230M With  $R_S = 0$

**APPLICATION INFORMATION**

**interoperability with 5-V CAN systems**

It is essential that the 3.3-V SN65HVD230M family performs seamlessly with 5-V transceivers because of the large number of 5-V devices installed. Figure 35 displays a test bus of a 3.3-V node with the SN65HVD230M, and three 5-V nodes: one for each of TI's SN65LBC031 and UC5350 transceivers, and one using a competitor X250 transceiver.



**Figure 35. 3.3-V/5-V CAN Transceiver Test Bed**



## APPLICATION INFORMATION

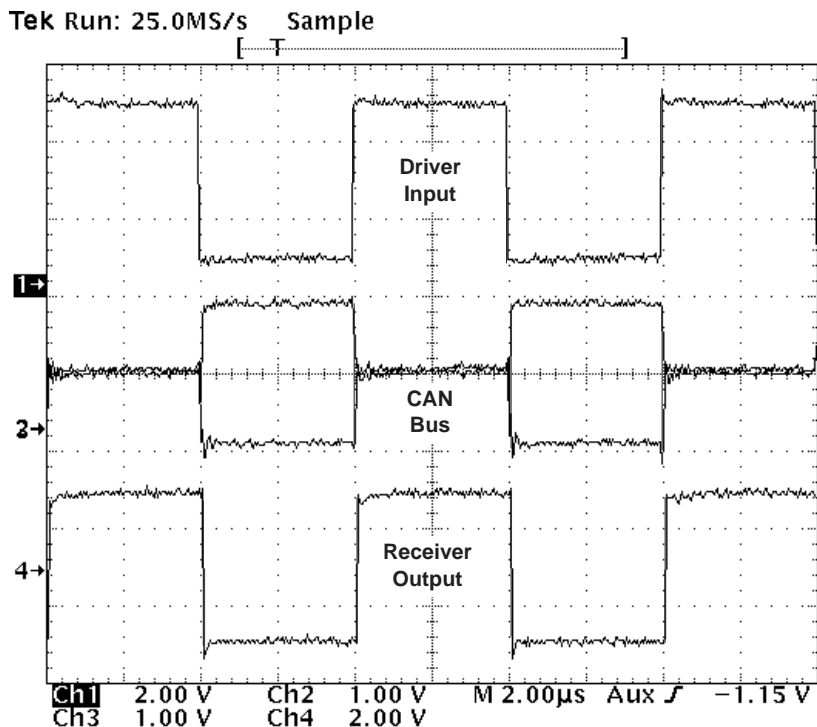


Figure 36. SN65HVD230M's Input, CAN Bus, and X250's RXD Output Waveforms

Figure 36 displays the SN65HVD230M's input signal, the CAN bus, and the competitor X250's receiver output waveforms. The input waveform from the Tektronix HFS-9003 Pattern Generator in Figure 35 to the SN65HVD230M is a 250-kbps pulse for this test. The circuit is monitored with Tektronix P6243, 1-GHz single-ended probes in order to display the CAN dominant and recessive bus states.

Figure 36 displays the 250-kbps pulse input waveform to the SN65HVD230M on channel 1. Channels 2 and 3 display CANH and CANL respectively, with their recessive bus states overlaying each other to clearly display the dominant and recessive CAN bus states. Channel 4 is the receiver output waveform of the competitor X250.

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
SN65HVD230MDREP	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	H230EP	<a href="#">Samples</a>
V62/06629-01XE	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	H230EP	<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) Only one of markings shown within the brackets will appear on the physical device.

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**TAPE AND REEL INFORMATION**

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN65HVD230MDREP	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1

**TAPE AND REEL BOX DIMENSIONS**

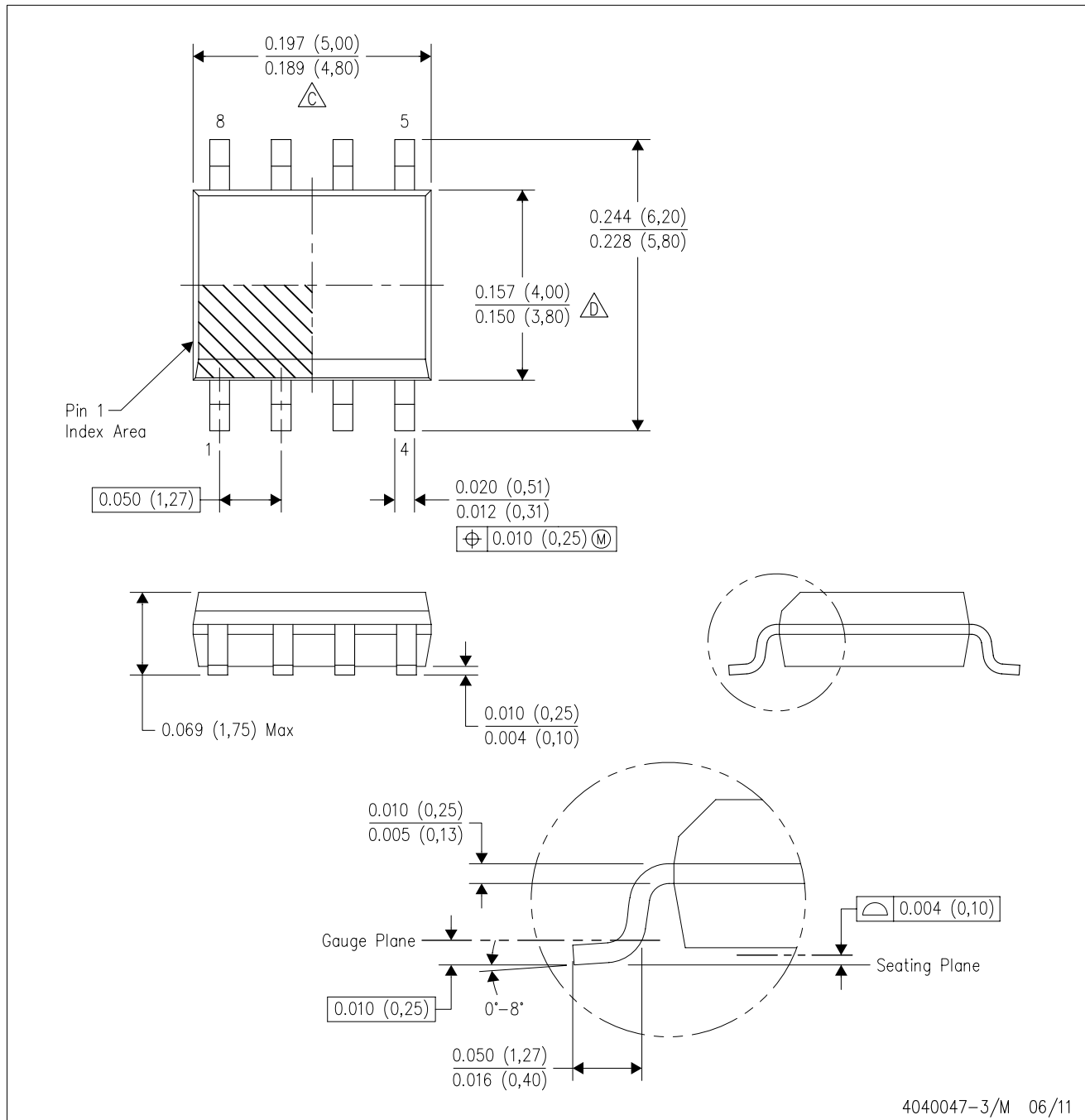


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN65HVD230MDREP	SOIC	D	8	2500	367.0	367.0	35.0

D (R-PDSO-G8)

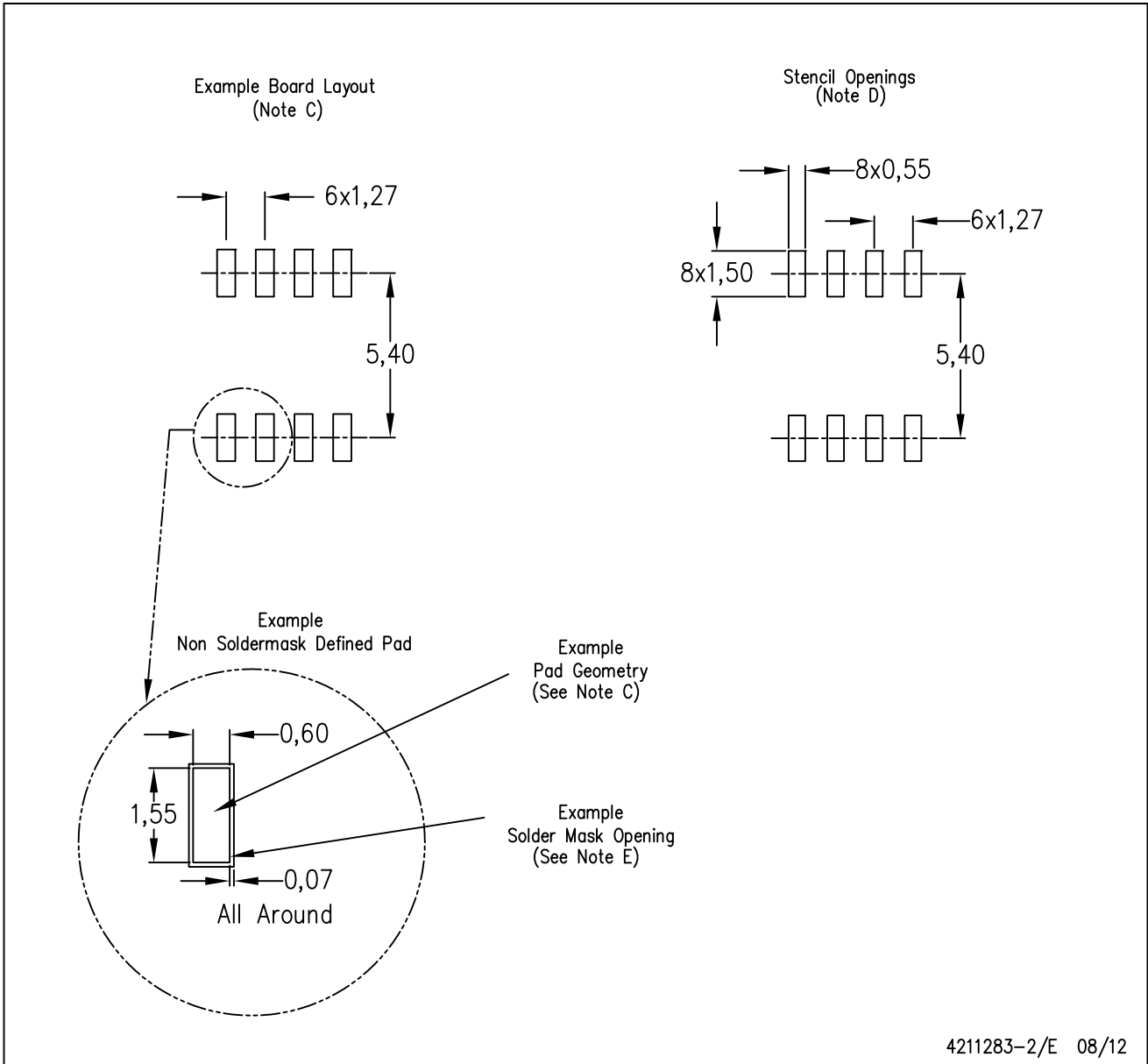
PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
  - D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
  - E. Reference JEDEC MS-012 variation AA.

D (R-PDSO-G8)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Publication IPC-7351 is recommended for alternate designs.
  - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
  - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

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